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(54) **LIGHT SENSING ELEMENT AND  
MANUFACTURING METHOD THEREOF**

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(57) **ABSTRACT**

The present invention provides a manufacturing method of a light sensing element. The method includes the following steps: providing a preformed structure, wherein the preformed structure includes a semiconductor structure and a bandpass filter layer stacked on the semiconductor structure; performing a laser cutting process on the preformed structure along a direction perpendicular to a surface of the bandpass filter layer so that the preformed structure is cut into a plurality of light sensing elements. Each light sensing element has a plurality of sidewalls. Each sidewall forms a scorched surface by the laser cutting process to block the entry of external light.

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